

L Number	Hits	Search Text	DB	Time stamp
1	61023	sidewall with (top or upper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 12:51
2	6470	((sidewall with (top or upper)) with plat\$9	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 12:52
3	45	((sidewall with (top or upper)) with plat\$9) with resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:00
4	964	((sidewall with (top or upper)) with plat\$9) same (metal or metallization or conduct\$4 or plating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:00
5	259	((sidewall with (top or upper)) with plat\$9) same (metal or metallization or conduct\$4 or plating)) same (etch\$4 or pattern\$4 or remov\$4 or mask\$4 or photolithograph\$7 or photoresist or photosensitiv\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:04
6	114	((sidewall with (top or upper)) with plat\$9) same (metal or metallization or conduct\$4 or plating)) same (etch\$4 or pattern\$4 or remov\$4 or mask\$4 or photolithograph\$7 or photoresist or photosensitiv\$4)) same (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:28
7	1	((sidewall with (top or upper)) with plat\$9) same (metal or metallization or conduct\$4 or plating)) same (etch\$4 or pattern\$4 or remov\$4 or mask\$4 or photolithograph\$7 or photoresist or photosensitiv\$4)) same (substrate or wafer)) same polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:29
8	5	((sidewall with (top or upper)) with plat\$9) same (metal or metallization or conduct\$4 or plating)) same polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:29
9	4	((sidewall with (top or upper)) with plat\$9) same (metal or metallization or conduct\$4 or plating)) same polyimide) not (((sidewall with (top or upper)) with plat\$9) same (metal or metallization or conduct\$4 or plating)) same (etch\$4 or pattern\$4 or remov\$4 or mask\$4 or photolithograph\$7 or photoresist or photosensitiv\$4)) same (substrate or wafer)) same polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:29
10	8131	polyimide with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:29
11	9341	polyimide with (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:29
12	1534	(polyimide with (copper or cu)) same (adhesion or adher\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:30

13	556	((polyimide with (copper or cu)) same (adhesion or adher\$4)) same (pattern\$4 or etch\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:30
14	33	((polyimide with (copper or cu)) same (adhesion or adher\$4)) same (pattern\$4 or etch\$4)) and 205/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:30
15	4	((polyimide with (copper or cu)) same (adhesion or adher\$4)) same (pattern\$4 or etch\$4)) and 205/\$.ccls.) and 216/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/17 13:31

L Number	Hits	Search Text	DB	Time stamp
1	71311	216/13-21.ccls. or 174/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 14:03
2	58	(216/13-21.ccls. or 174/\$.ccls.) and (polyimide near3 (micron or micrometer or nanometer or nm))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 14:03

L Number	Hits	Search Text	DB	Time stamp
1	9773	photoresist with thin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 12:59
2	7712	polyimide with thin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 12:59
3	453	((polyimide with thin) same plating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 13:00
4	24	((polyimide with thin) same plating) same adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 13:19
5	42	((polyimide with thin) same plating) same (micron or micrometer or nanometer or nm)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 13:30
6	1352	polyimide near3 (micron or micrometer or nanometer or nm)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 13:30
7	70	(polyimide near3 (micron or micrometer or nanometer or nm)) same (plating plated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 13:30
8	3	((polyimide near3 (micron or micrometer or nanometer or nm)) same (plating plated)) same adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 13:31
9	0	((polyimide near3 (micron or micrometer or nanometer or nm)) same (plating plated)) same (.1 .05 .15 .2 .25 .3 .35 .4 .45 .5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 13:31
11	51	((polyimide near3 (micron or micrometer or nanometer or nm)) same (plating plated)) same (nickel or cu or ni or copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/21 13:32